

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.22	100.0	1.02
			Subtotal	0.22	100	1.02
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.03	0.05
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01	0.03	0.05
	Copper alloy	Iron (Fe)	7439-89-6	0.04	0.1	0.17
	Copper alloy	Copper (Cu)	7440-50-8	38.17	99.84	173.92
			Subtotal	38.23	100	174.19
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.21	3.8	10.09
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.5	6.0	15.93
	Filler	Silica fused	60676-86-0	52.46	90.0	239.02
	Carbon Black	Carbon black	1333-86-4	0.12	0.2	0.53
			Subtotal	58.29	100	265.57
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.63	100.0	12
			Subtotal	2.63	100	12
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.37	100.0	1.7
			Subtotal	0.37	100	1.7
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.01	2.0	0.02
	Lead alloy	Silver (Ag)	7440-22-4	0.01	2.5	0.03
	Lead alloy	Lead (Pb)	7439-92-1	0.24	95.5	1.1
			Subtotal	0.26	100	1.15
			Total	100	100	455.63

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